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(12) **United States Design Patent** (10) **Patent No.:** **US D969,761 S**
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(54) **POWER SEMICONDUCTOR MODULE**

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(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
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2224/08054; H01L 23/58; H05B 41/14;
G02B 6/4256; G02B 6/4257; G02B
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H05K 1/142; H05K 1/144; H05K 1/18;
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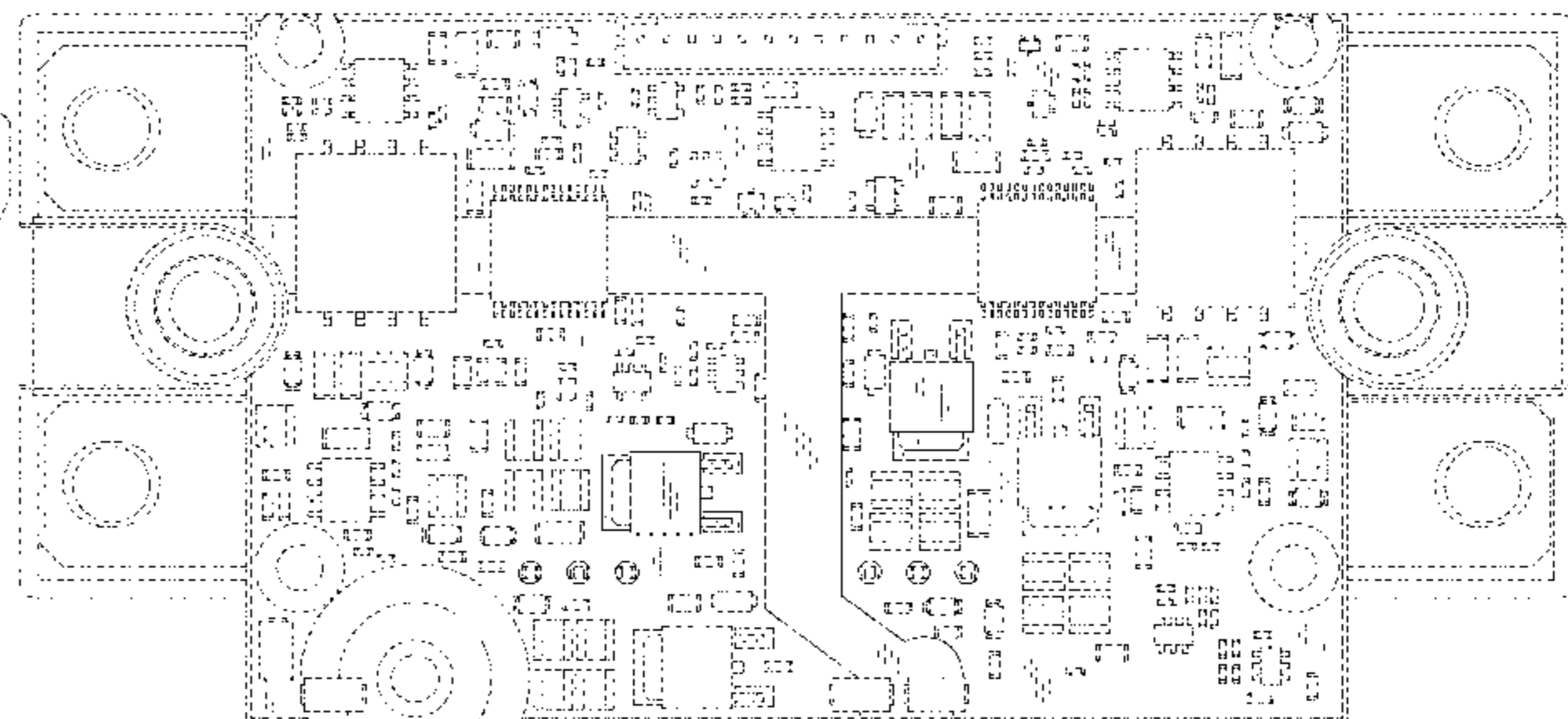
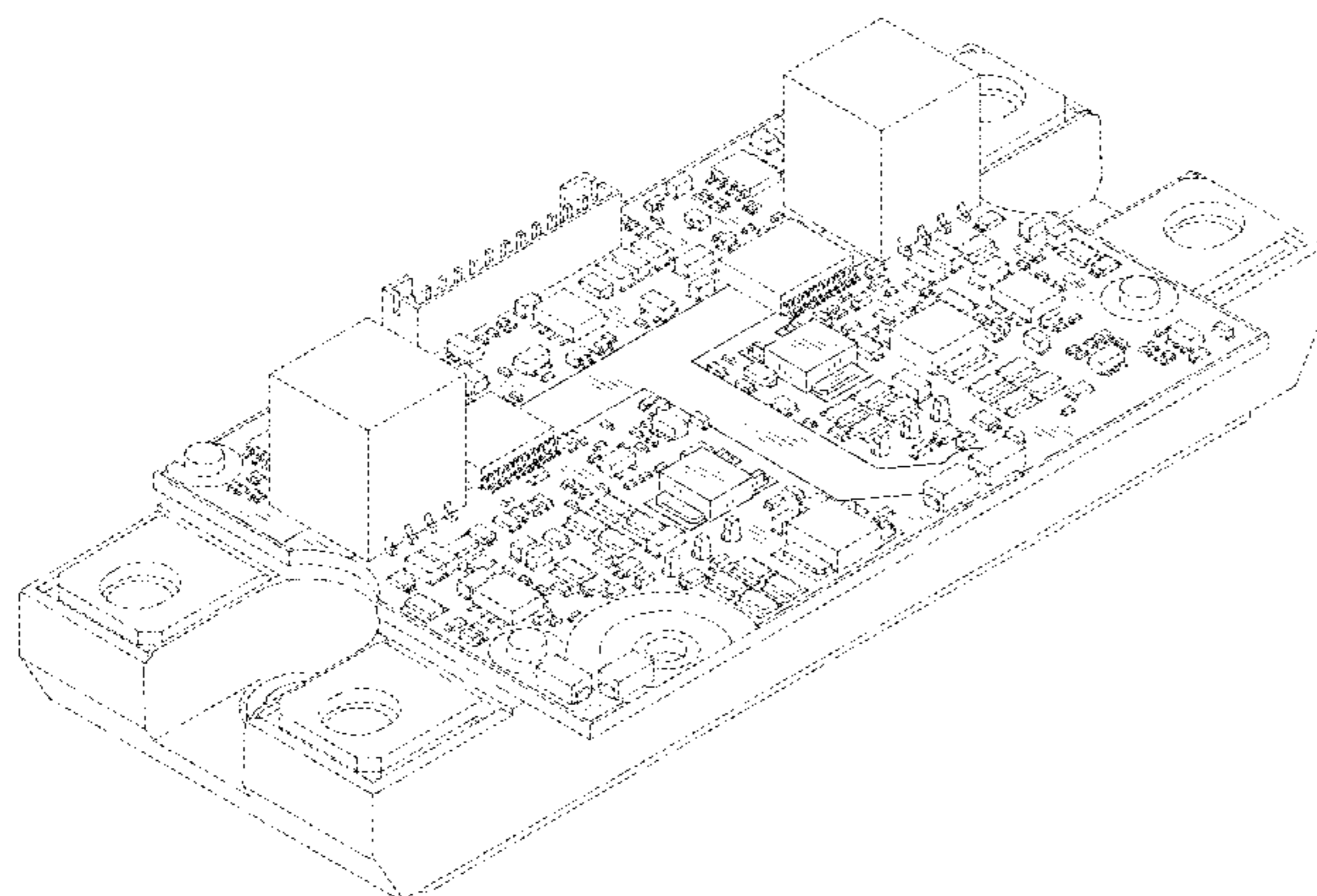
(57) **CLAIM**

The ornamental design for a power semiconductor module, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and left side perspective view of a power semiconductor module showing our new design; FIG. 2 is a front view thereof; FIG. 3 is a rear view thereof; FIG. 4 is a top plan view thereof; FIG. 5 is a right side view thereof; and, FIG. 6 is a left side view thereof. The even broken lines illustrate portions of the power semiconductor module that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



(58) **Field of Classification Search**
 CPC H05K 1/182; H05K 1/026; H02B 1/015;
 H02B 1/00
 See application file for complete search history.

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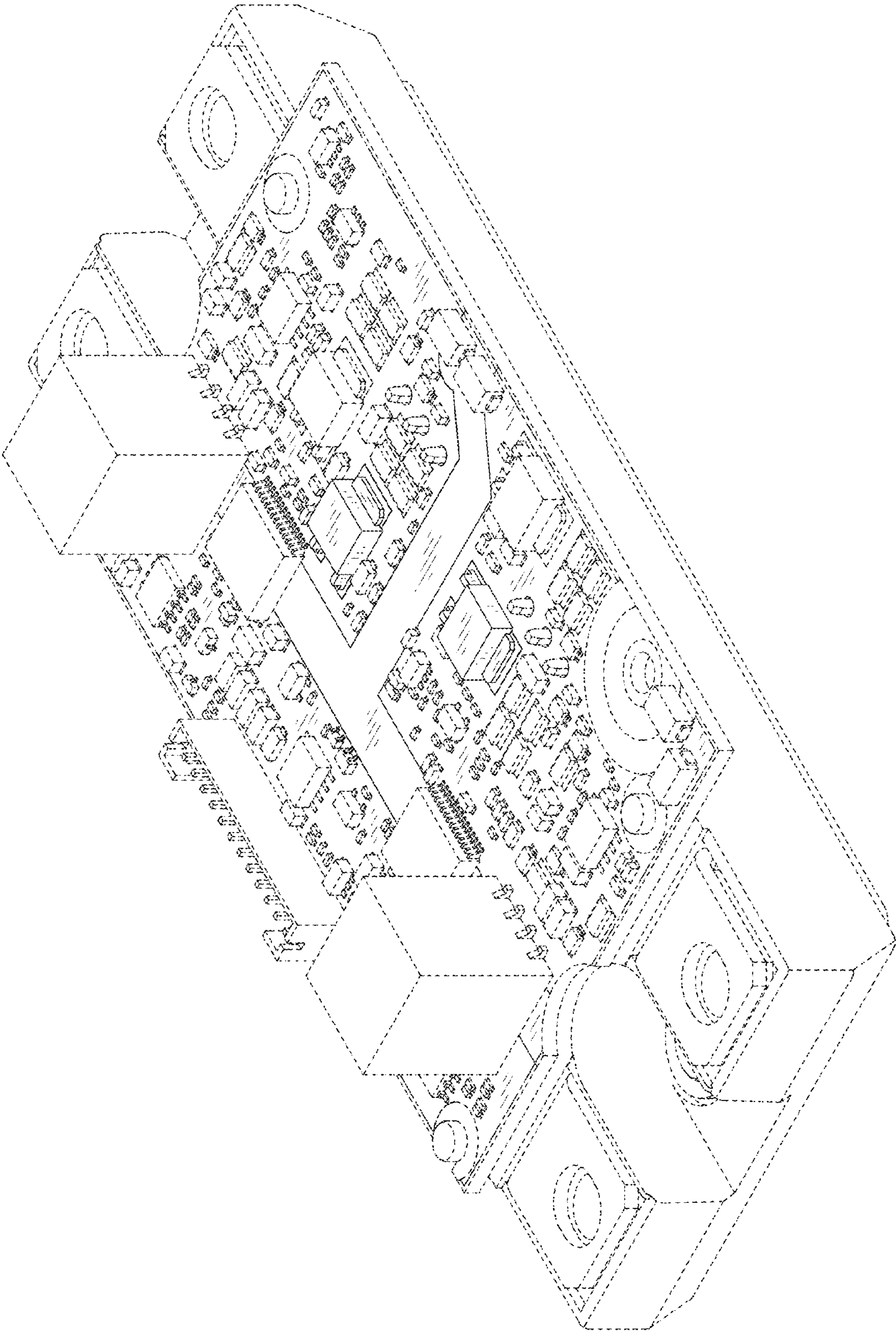


FIG.1

FIG.2

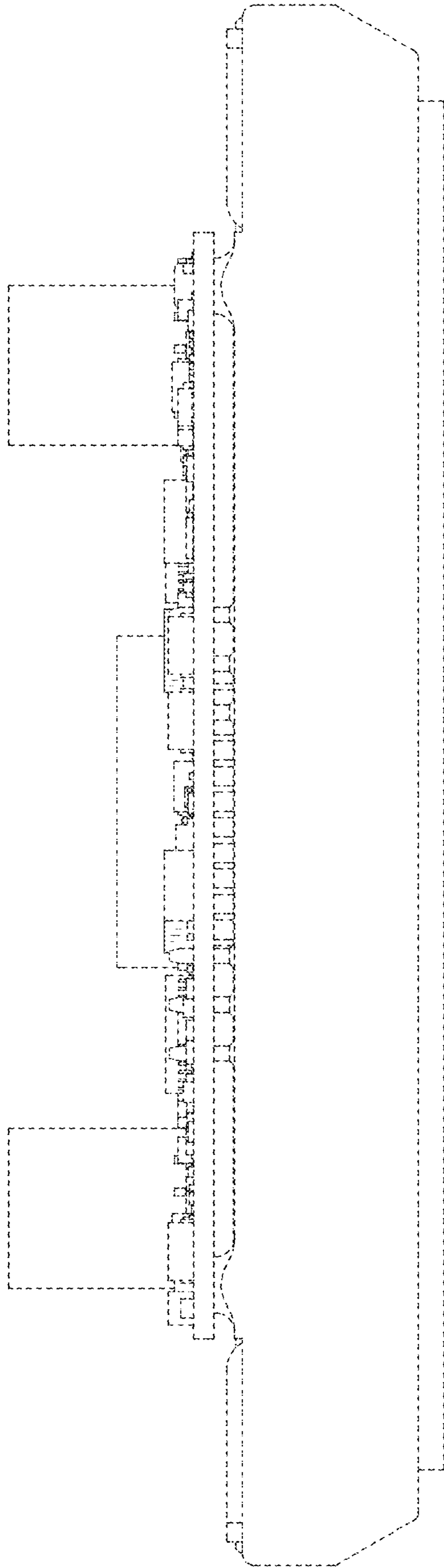


FIG. 3

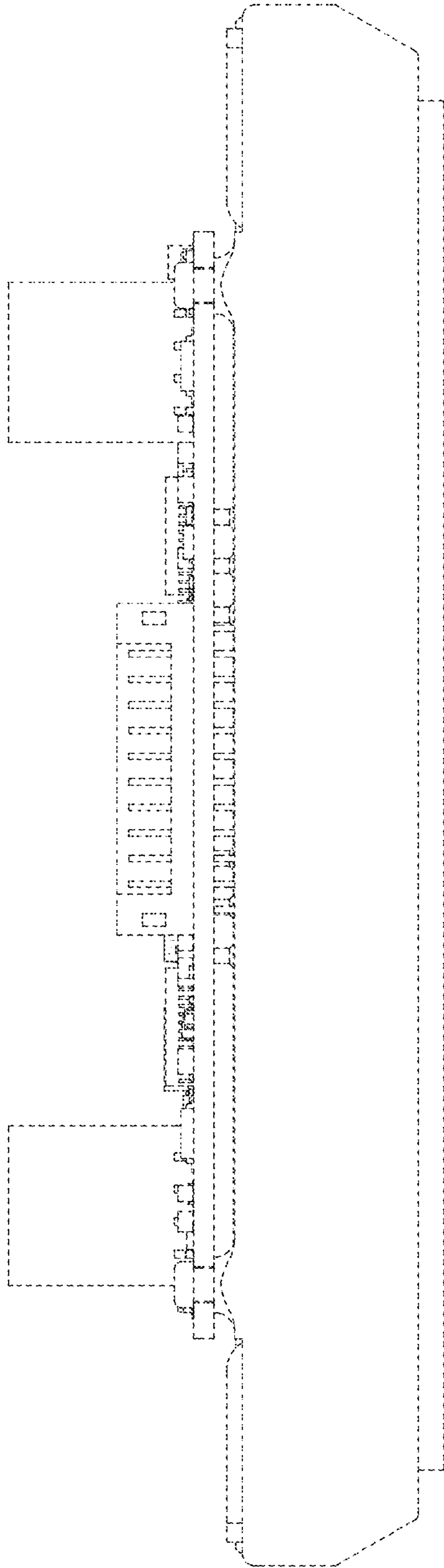
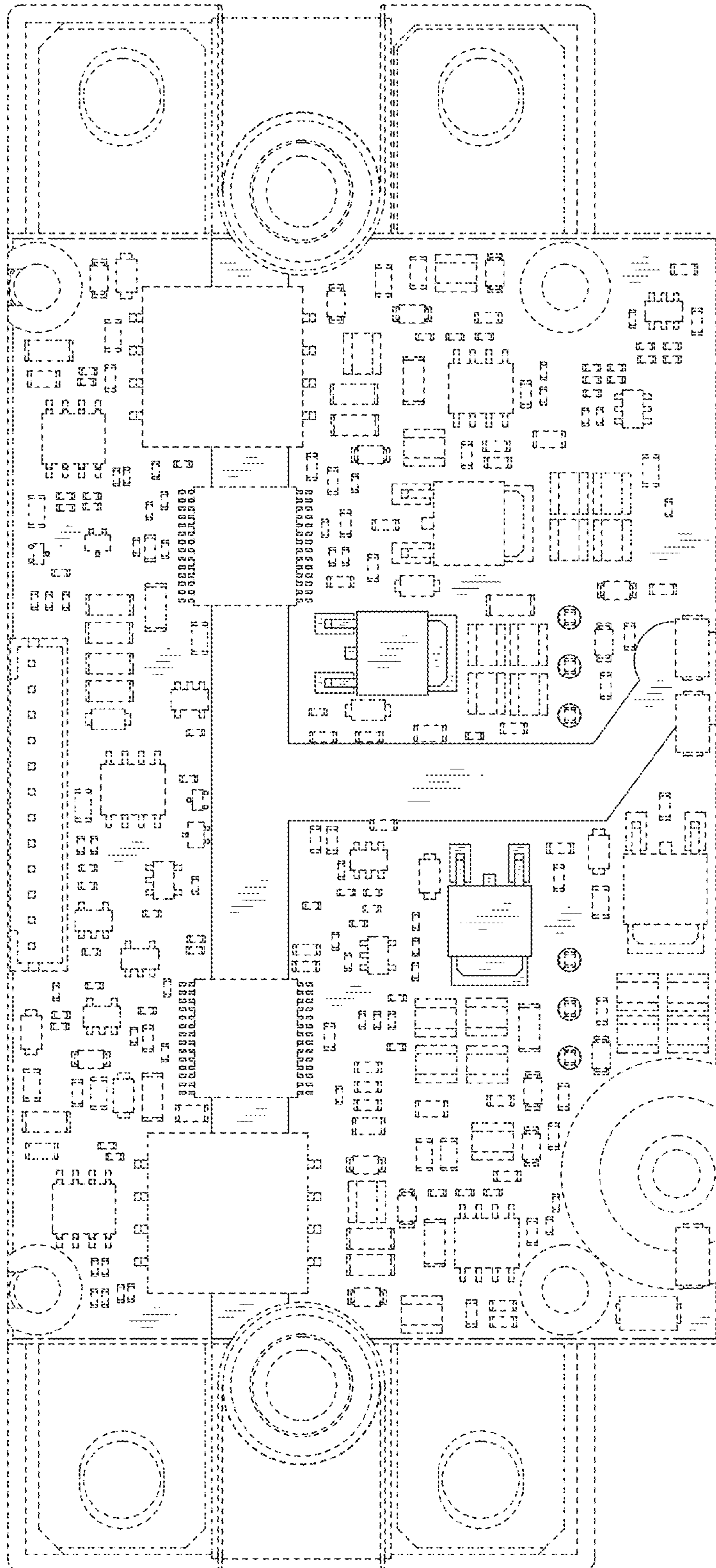


FIG.4



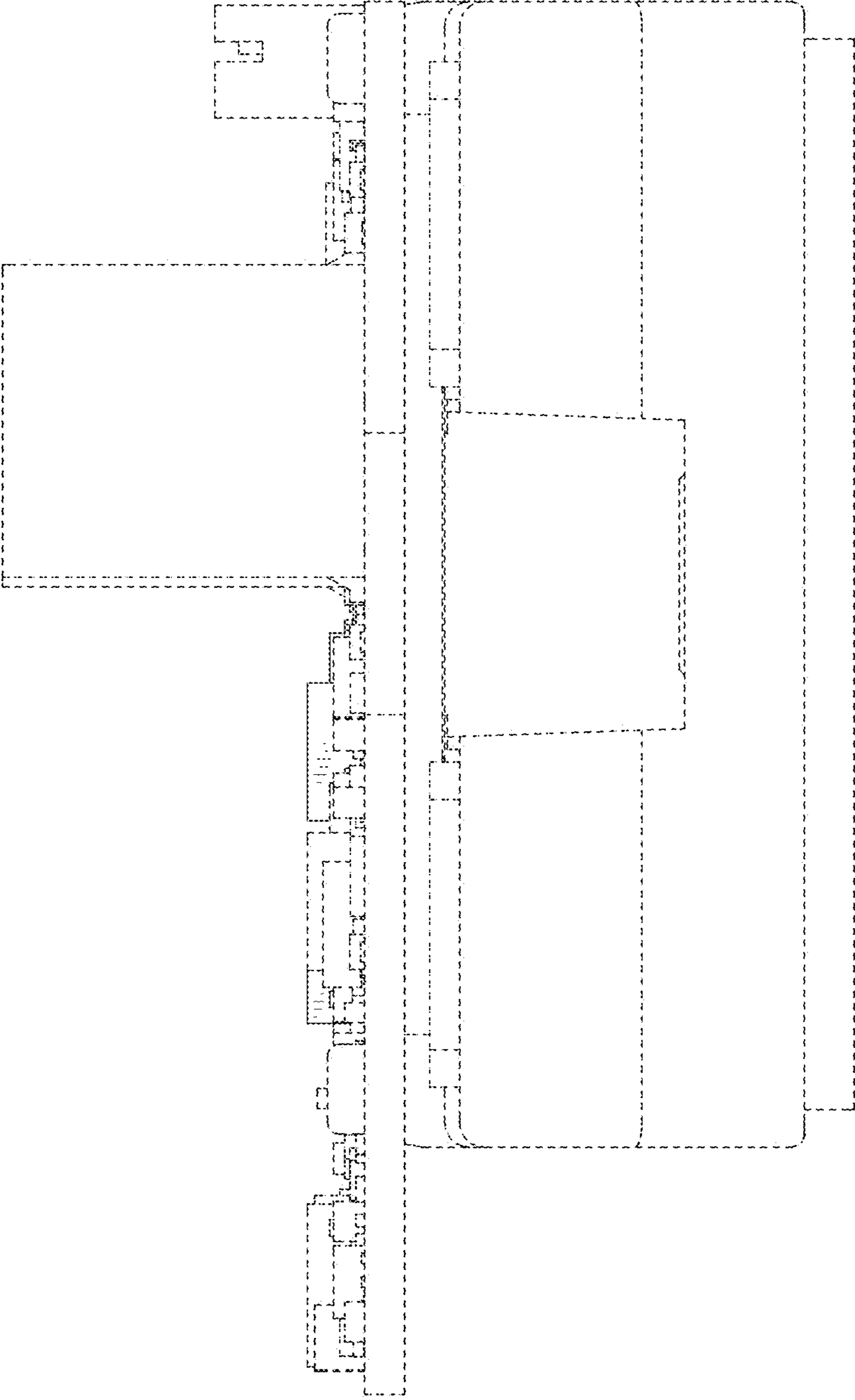


FIG. 5

FIG. 6

